

## Patent Abstracts of Japan

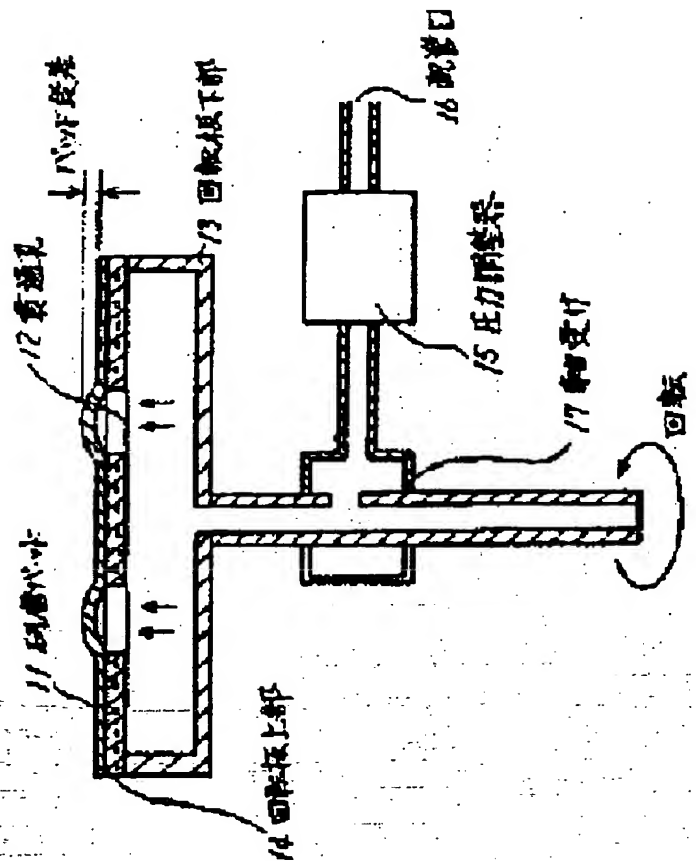
PUBLICATION NUMBER : 03259520  
 PUBLICATION DATE : 19-11-91  
 APPLICATION DATE : 08-03-90  
 APPLICATION NUMBER : 02058605

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INT.CL. : H01L 21/304 B24B 37/04

TITLE : ROTARY POLISHING EQUIPMENT



**ABSTRACT :** **PURPOSE:** To enable a polishing process from rough polishing to final polishing by one time intermittent polishing of a single abrasive pad, by forming a step- difference on the surface of the abrasive pad on a rotary plate, and installing a mechanism which controls the height of the step-difference at the time of polishing.

**CONSTITUTION:** Penetrating holes 12 whose diameter is 6 mm are arranged on the upper part 14 of a metal rotary plate. The density is 0.5 hole per centimeter. Thereon a polyester abrasive pad 11 of 0.8mm in thickness is stuck. The lower part 13 of the rotary plate 13 is equipped with a bearing 17 capable of keeping air-tightness. Compressed air is supplied from the outside, via a compressed air feeding inlet 16 in the outside. A pressure adjusting apparatus 15 is installed to adjust the air pressure according to an electric signal from the outside. Pressure is applied to the rear of the pad 11, and deformation is locally generated, thereby attaining a step-difference shape, which can be adjusted from the outside. Hence a single process of automatic polishing from rough polishing to final polishing is realized by one time intermittent polishing of the single pad 11.

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